

## WHAT IS CLAIMED IS:

1. An epoxy resin composition for packaging a semiconductor element, obtained by formulating:

(A) phenol aralkyl type of epoxy resin having a biphenylene  
5 unit in the main chain;

(B) a phenolic resin;

(C) a curing accelerator;

(D) an inorganic filler; and

(E) an oxidized polyethylene wax having a drop point within  
10 a range of from 60 to 140 degree C, an acid value within a range  
of from 10 to 100 (mg KOH/g), a number average molecular weight  
within a range of from 500 to 20,000, and a mean particle size  
within a range of from 5 to 100  $\mu$ m.

15 2. An epoxy resin composition for packaging a semiconductor  
element, obtained by formulating:

(A) an epoxy resin;

(B) a phenol aralkyl type of phenolic resin having a  
biphenylene unit in the main chain;

20 (C) a curing accelerator;

(D) an inorganic filler; and

(E) an oxidized polyethylene wax having a drop point within  
a range of from 60 to 140 degree C, an acid value within a range  
of from 10 to 100 (mg KOH/g), a number average molecular weight  
25 within a range of from 500 to 20,000, and a mean particle size  
within a range of from 5 to 100  $\mu$ m.

3. The epoxy resin composition for packaging a semiconductor element, according to claim 2,

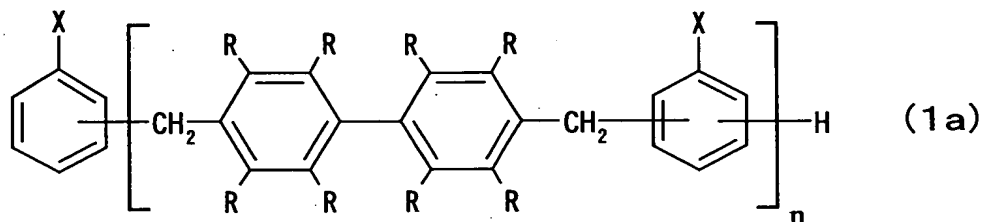
wherein the said (A) epoxy is a phenol aralkyl type of epoxy resin having a biphenylene unit in the main chain.

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4. The epoxy resin composition for packaging a semiconductor element, according to claim 1,

wherein the said (A) epoxy resin has a structure represented by general formula (1a):

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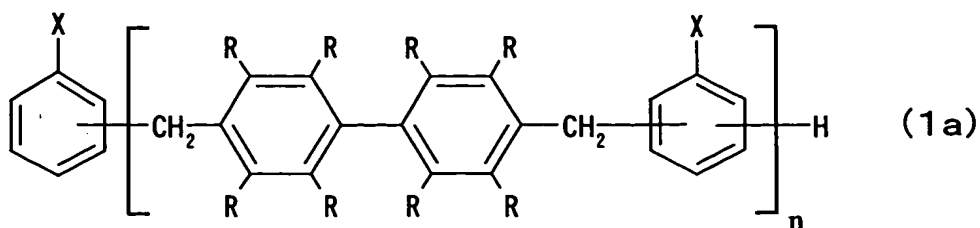


(wherein, Rs, each of which may be same or different, represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.)

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5. The epoxy resin composition for packaging a semiconductor element, according to claim 2,

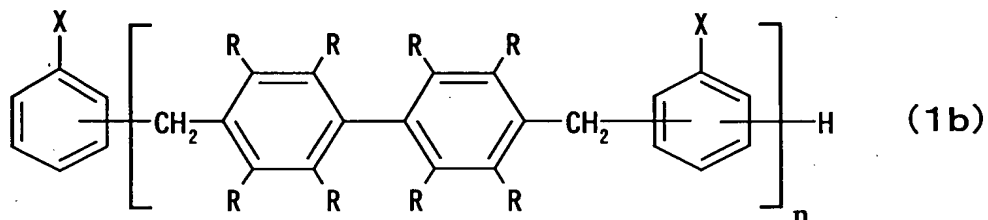
wherein the said (A) epoxy resin has a structure represented by general formula (1a):



(wherein, Rs, each of which may be same or different, represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.)

6. The epoxy resin composition for packaging a semiconductor element, according to claim 1,

wherein the said (B) phenolic resin has a structure represented by general formula (1b):

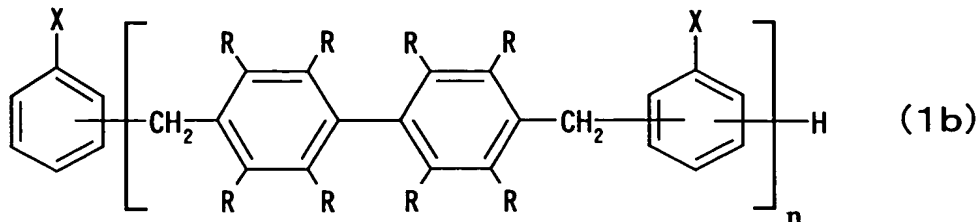


(wherein, Rs, each of which may be same or different, represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.)

7. The epoxy resin composition for packaging a semiconductor element, according to claim 2,

wherein the said (B) phenolic resin has a structure

represented by general formula (1b):



(wherein, Rs, each of which may be same or different, represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.)

8. The epoxy resin composition for packaging a semiconductor element, according to claim 1,

10 wherein content of said (E) oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

9. The epoxy resin composition for packaging a semiconductor element, according to claim 2,

15 wherein content of said (E) oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

20 10. A semiconductor device, which is formed by employing said epoxy resin composition according to claim 1 to package a semiconductor element included therein.

11. A semiconductor device, which is formed by employing said epoxy resin composition according to claim 2 to package a semiconductor element included therein.